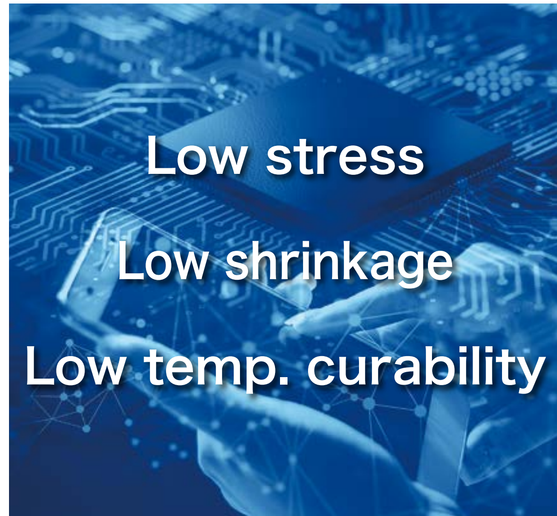
Panasonic INDUSTRY



Applications
IC Package/Mobile

Over-molding and wafer back-coating of advanced semiconductor packages, such as WLPs (FOWLPs and FIWLPs) and PLPs, for sophisticated mobile and wearable devices.

LEXCM CF

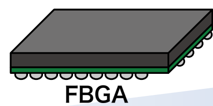
CV8511CUB

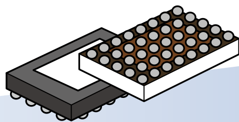
Encapsulation materials for FOWLP/PLP

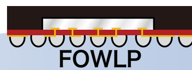
Available in forms of granule according to the required encapsulation thickness and size, enabling compression molding and lamination molding. Respond to growing size and low warpage of thin packages and contribute to the increased productivity of advanced semiconductor packages.

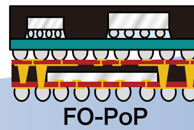
FOWLP Technology Trend

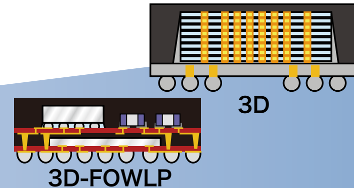
Contribute to low warpage and thinner product


FBGA




FOWLP


FO-PoP

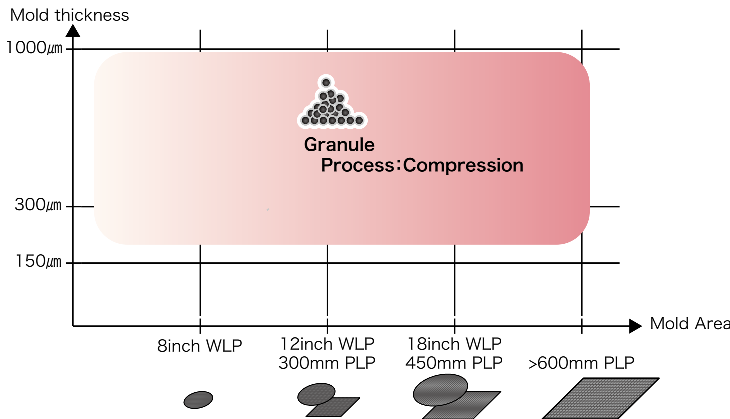

3D-FOWLP

3D

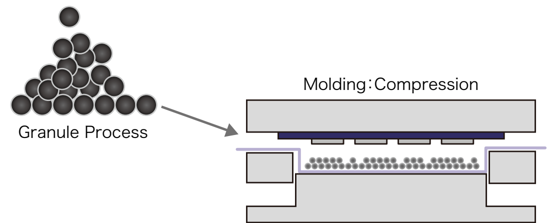
FOWLP tech.

Line-up and corresponding package

We have wide range of Encapsulation Line-up for WLP/PLP



Encapsulation method



General properties

Item	Unit	LEXCM CF CV8511CUB	LEXCM CF X85U-PT1-AP
Mold size	–	Wafer Level / Panel Level	
Process	–	Chip First / Chip Last	
Form	–	Granule	Granule
Mold shrinkage	%	0.15	0.07
Tg	℃	210	174
C.T.E.1	ppm/℃	8	7
C.T.E.2	ppm/℃	56	25
Flexural modulus (25℃)	GPa	8	30

Please see our website for Notes before you use.

The above data are typical values and not guaranteed values.

industrial.panasonic.com/ww/electronic-materials

Panasonic Industry CV8511CUB

Panasonic Industry Co., Ltd. Electronic Materials Business Division

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